Features

- Single Voltage Operation
 - 5V Read
 - 5V Reprogramming
- Fast Read Access Time 90 ns
- Internal Program Control and Timer
- 16K bytes Boot Block With Lockout
- Fast Erase Cycle Time 10 seconds
- Byte By Byte Programming 50 μs/Byte
- Hardware Data Protection
- DATA Polling For End Of Program Detection
- Low Power Dissipation
 - 50 mA Active Current
 - 100 μA CMOS Standby Current
- Typical 10,000 Write Cycles

Description

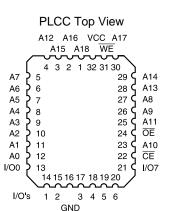
The AT49F040 is a 5-volt-only in-system Flash Memory. Its 4 megabits of memory is organized as 524,288 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 90 ns with power dissipation of just 275 mW over the commercial temperature range. When the device is deselected, the CMOS standby current is less than $100 \, \mu A$.

To allow for simple in-system reprogrammability, the AT49F040 does not require high input voltages for programming. Five-volt-only commands determine the read and programming operation of the device. Reading data out of the device is similar to reading from an EPROM. Reprogramming the AT49F040 is performed by erasing the entire 4 megabits of memory and then programming on a byte by byte basis. The byte programming time is a fast $50\,\mu s$. The end of a program cycle can be optionally detected by the DATA polling feature. Once the end of a byte program cycle has been detected, a new access for a read or program can begin. The typical number of program and erase cycles is in excess of 10,000 cycles.

(continued)

Pin Configurations

Pin Name	Function
A0 - A18	Addresses
CE	Chip Enable
ŌE	Output Enable
WE	Write Enable
I/O0 - I/O7	Data Inputs/Outputs



DIP Top View

	- 1		\cup		ı	
A18	d	1		32	þ	VCC
A16	d	2		31	Þ	WE
A15	d	3		30	Þ	A17
A12	d	4		29	Þ	A14
Α7	d	5		28	Þ	A13
A6	d	6		27	þ	A8
A5	d	7		26	þ	A9
A4	d	8		25	þ	A11
АЗ	d	9		24	þ	ŌĒ
A2	d	10		23	þ	A10
Α1	d	11		22	þ	CE
A0	Ь	12		21	þ	1/07
I/O0	Ь	13		20	þ	I/O6
I/O1	d	14		19	Ь	I/O5
1/02	d	15		18	þ	I/O4
GND	d	16		17	þ	I/O3
	- [

TSOP Top View **Type 1**

A11	🗐	$\overline{\bigcirc}$	1 .	32		Þ		ŌE	
A8	A9 🗄	\circ	3	30	31	Б	A10	CE	
	A13 日	4	-		29	Ė	I /O7		
A14	A17 🗄	6	5	28	27	Б	I/O5	I/O6	
WE			7	26		Ė		I /O4	
A18	vcc 🖁	8	9	24	25	Б	I/O3	GND	
	A16 🖯	10	-		23	E	I /O2		
A15	A12 🗟	12	11	22	21	Б	I/O0	I/O1	
Α7	9	14	13	20	19	E	A1	A0	
A5	A6 🖁		15	18		Б		A2	
,	$\Delta A \Box$	16	10	. •	17	ь	АЗ	/12	

4 Megabit (512K x 8) 5-volt Only CMOS Flash Memory

Preliminary

0359C



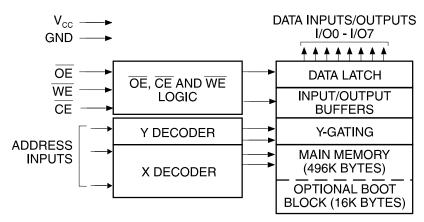


Description (Continued)

The optional 16K bytes boot block section includes a reprogramming write lock out feature to provide data integrity. The boot sector is designed to contain user secure

code, and when the feature is enabled, the boot sector is permanently protected from being reprogrammed.

Block Diagram



Device Operation

READ: The AT49F040 is accessed like an EPROM. When CE and OE are low and WE is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever CE or OE is high. This dual-line control gives designers flexibility in preventing bus contention.

ERASURE: Before a byte can be reprogrammed, the 512K bytes memory array (or 496K bytes if the boot block featured is used) must be erased. The erased state of the memory bits is a logical "1". The entire device can be erased at one time by using a 6-byte software code. The software chip erase code consists of 6-byte load commands to specific address locations with a specific data pattern (please refer to the Chip Erase Cycle Waveforms).

After the software chip erase has been initiated, the device will internally time the erase operation so that no external clocks are required. The maximum time needed to erase the whole chip is t_{EC} . If the boot block lockout feature has been enabled, the data in the boot sector will not be erased.

BYTE PROGRAMMING: Once the memory array is erased, the device is programmed (to a logical "0") on a byte-by-byte basis. Please note that a data "0" cannot be programmed back to a "1"; only erase operations can convert "0"s to "1"s. Programming is accomplished via the internal device command register and is a 4 bus cycle operation (please refer to the Command Definitions table). The device will automatically generate the required internal program pulses.

The program cycle has addresses latched on the falling edge of WE or CE, whichever occurs last, and the data latched on the rising edge of WE or CE, whichever occurs first. Programming is completed after the specified tBP cy-

cle time. The DATA polling feature may also be used to indicate the end of a program cycle.

BOOT BLOCK PROGRAMMING LOCKOUT: The device has one designated block that has a programming lockout feature. This feature prevents programming of data in the designated block once the feature has been enabled. The size of the block is 16K bytes. This block, referred to as the boot block, can contain secure code that is used to bring up the system. Enabling the lockout feature will allow the boot code to stay in the device while data in the rest of the device is updated. This feature does not have to be activated; the boot block's usage as a write protected region is optional to the user. The address range of the boot block is 00000H to 03FFFH.

Once the feature is enabled, the data in the boot block can no longer be erased or programmed. Data in the main memory block can still be changed through the regular programming method. To activate the lockout feature, a series of six program commands to specific addresses with specific data must be performed. Please refer to the Command Definitions table.

BOOT BLOCK LOCKOUT DETECTION: A software method is available to determine if programming of the boot block section is locked out. When the device is in the software product identification mode (see Software Product Identification Entry and Exit sections) a read from address location 00002H will show if programming the boot block is locked out. If the data on I/O0 is low, the boot block can be programmed; if the data on I/O0 is high, the program lockout feature has been activated and the block cannot be programmed. The software product identification code should be used to return to standard operation.

(continued)

Device Operation (Continued)

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

DATA POLLING: The AT49F040 features DATA polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. DATA polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to DATA polling the AT49F040 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT49F040 in the following ways: (a) VCC sense: if VCC is below 3.8V (typical), the program function is inhibited. (b) Program inhibit: holding any one of OE low, CE high or WE high inhibits program cycles. (c) Noise filter: pulses of less than 15 ns (typical) on the WE or CE inputs will not initiate a program cycle.

Command Definition (in Hex)

Command Sequence	Bus Cycles	1st I Cy		2nd Cy		3rd Cy		4th Cy	Bus cle	5th I		6th I Cy	
		Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data
Read	1	Addr	D _{OUT}										
Chip Erase	6	5555	AA	2AAA	55	5555	80	5555	AA	2AAA	55	5555	10
Byte Program	4	5555	AA	2AAA	55	5555	A0	Addr	D _{IN}				
Boot Block Lockout ⁽¹⁾	6	5555	AA	2AAA	55	5555	80	5555	AA	2AAA	55	5555	40
Product ID Entry	3	5555	AA	2AAA	55	5555	90						
Product ID Exit ⁽²⁾	3	5555	AA	2AAA	55	5555	F0						
Product ID Exit ⁽²⁾	1	XXXX	F0										

- Note: 1. The 16K byte boot sector has the address range 00000H to 03FFFH.
 - 2. Either one of the Product ID exit commands can be used.

Absolute Maximum Ratings*

Temperature Under Bias55°C to +125°C	
Storage Temperature65°C to +150°C	
All Input Voltages (including NC Pins) with Respect to Ground0.6V to +6.25V	
All Output Voltages with Respect to Ground0.6V to V _{CC} + 0.6V	
Voltage on $\overline{\text{OE}}$ with Respect to Ground0.6V to + 13.5V	

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





DC and AC Operating Range

		AT49F040-90	AT49F040-12	AT49F040-15
Operating	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C
Temperature (Case)	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
V _{CC} Power Supply		5V ± 10%	$5V \pm 10\%$	$5V \pm 10\%$

Operating Modes

Mode	CE	OE	WE	Ai	1/0
Read	VIL	VIL	VIH	Ai	D _{OUT}
Program (2)	V_{IL}	V_{IH}	V_{IL}	Ai	D _{IN}
Standby/Write Inhibit	V_{IH}	X ⁽¹⁾	Χ	X	High Z
Program Inhibit	Χ	Χ	V_{IH}		
Program Inhibit	Χ	V_{IL}	Χ		
Output Disable	Χ	V_{IH}	Χ		High Z
Product Identification					
Hardware	VIL	VIL	Var	A1 - A18 = V_{IL} , A9 = V_{H} , (3) A0 = V_{IL}	Manufacturer Code (4)
Tiaiuwaie	VIL	VIL	V _{IH}	A1 - A18 = V_{IL} , A9 = V_{H} , $^{(3)}$ A0 = V_{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				$A0 = V_{IL}, A1 - A18 = V_{IL}$	Manufacturer Code (4)
Sultware (9)				$A0 = V_{IH}, A1 - A18 = V_{IL}$	Device Code (4)

Notes: 1. X can be V_{IL} or V_{IH} .

2. Refer to AC Programming Waveforms.

3. $V_H = 12.0V \pm 0.5V$.

- 4. Manufacturer Code: 1FH, Device Code: 13H
- 5. See details under Software Product Identification Entry/Exit.

DC Characteristics

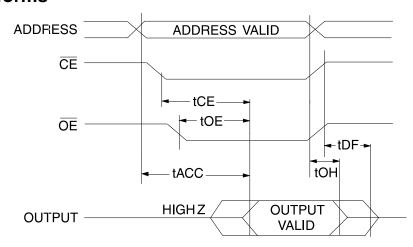
Symbol	Parameter	Condition		Min	Max	Units
ILI	Input Load Current	$V_{IN} = 0V$ to V_{CC}			10	μΑ
ILO	Output Leakage Current	$V_{I/O} = 0V$ to V_{CC}			10	μΑ
las.	Var Standby Current CMOS	$\overline{\text{CE}} = \text{V}_{\text{CC}} - 0.3 \text{V to V}_{\text{CC}}$ Com.			100	μΑ
I _{SB1}	V _{CC} Standby Current CMOS	CE = ACC - 0.3A to ACC	Ind.		300	μΑ
I _{SB2}	V _{CC} Standby Current TTL	CE = 2.0V to Vcc			3	mA
Icc (1)	Vcc Active Current	f = 5 MHz; IOUT = 0 mA			50	mA
VIL	Input Low Voltage				0.8	V
VIH	Input High Voltage			2.0		V
VoL	Output Low Voltage	I _{OL} = 2.1 mA			.45	V
V _{OH1}	Output High Voltage	Ι _{ΟΗ} = -400 μΑ		2.4		V
V _{OH2}	Output High Voltage CMOS	$I_{OH} = -100 \mu\text{A}; V_{CC} = 4.5 \text{V}$		4.2		V

Note: 1. In the erase mode, I_{CC} is 90 mA.

AC Read Characteristics

		AT49F	AT49F040-90		AT49F040-12		AT49F040-15	
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Units
tACC	Address to Output Delay		90		120		150	ns
t _{CE} (1)	CE to Output Delay		90		120		150	ns
toe (2)	OE to Output Delay	0	40	0	50	0	70	ns
t _{DF} (3, 4)	CE or OE to Output Float	0	25	0	30	0	40	ns
toH	Output Hold from OE, CE or Address, whichever occurred first	0		0		0		ns

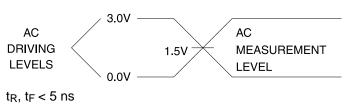
AC Read Waveforms (1, 2, 3, 4)



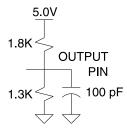
Notes: 1. $\overline{\text{CE}}$ may be delayed up to t_{ACC} - t_{CE} after the address transition without impact on t_{ACC} .

- 2. OE may be delayed up to t_{CE} t_{OE} after the falling edge of CE without impact on t_{CE} or by t_{ACC} t_{OE} after an address change without impact on t_{ACC}.
- 3. t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first $(C_L = 5 \text{ pF})$.
- 4. This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



Output Test Load



Pin Capacitance (f = 1 MHz, T = 25° C) (1)

	Тур	Max	Units	Conditions
C _{IN}	4	6	pF	$V_{IN} = 0V$
Соит	8	12	pF	$V_{OUT} = 0V$

Note: 1. This parameter is characterized and is not 100% tested.



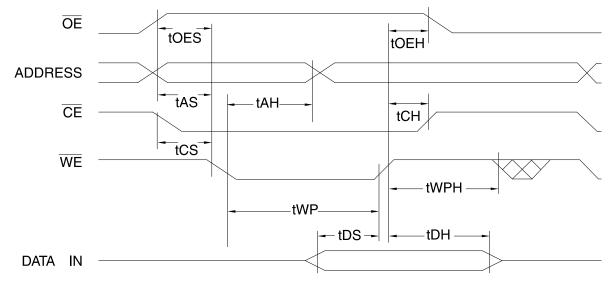


AC Byte Load Characteristics

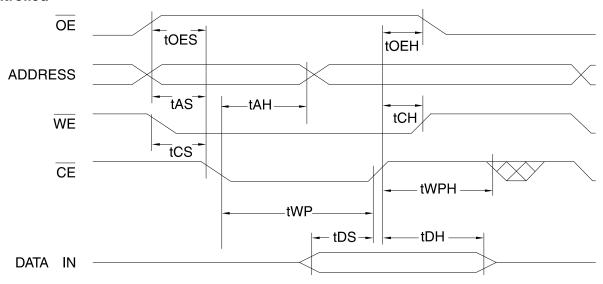
Symbol	Parameter	Min	Max	Units
tas, toes	Address, OE Set-up Time	0		ns
tah	Address Hold Time	50		ns
tcs	Chip Select Set-up Time	0		ns
tch	Chip Select Hold Time	0		ns
twp	Write Pulse Width (WE or CE)	90		ns
t _{DS}	Data Set-up Time	50		ns
tDH, tOEH	Data, OE Hold Time	0		ns
twpH	Write Pulse Width High	90		ns

AC Byte Load Waveforms

WE Controlled



CE Controlled

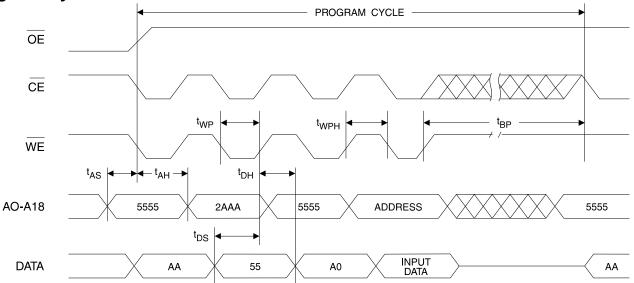


AT49F040

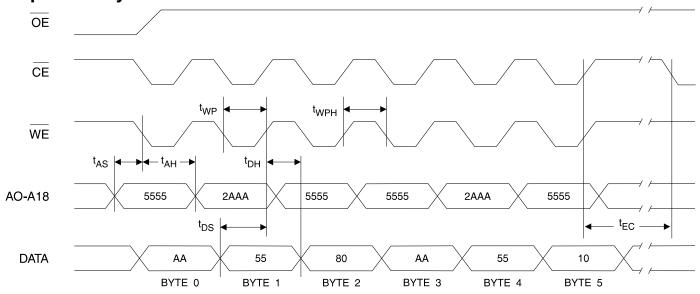
Program Cycle Characteristics

Symbol	Parameter	Min	Тур	Max	Units
t _{BP}	Byte Programming Time		10	50	μs
tas	Address Set-up Time	0			ns
t _{AH}	Address Hold Time	50			ns
t _{DS}	Data Set-up Time	50			ns
tDH	Data Hold Time	0			ns
twp	Write Pulse Width	90			ns
twph	Write Pulse Width High	90			ns
tEC	Erase Cycle Time			10	seconds

Program Cycle Waveforms



Chip Erase Cycle Waveforms



Note: $\overline{\text{OE}}$ must be high only when $\overline{\text{WE}}$ and $\overline{\text{CE}}$ are both low.





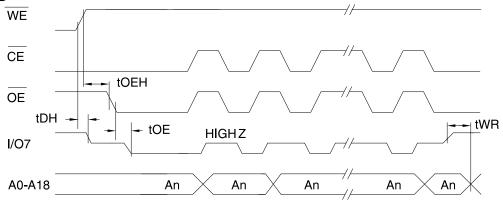
Data Polling Characteristics (1)

Symbol	Parameter	Min	Тур	Max	Units
t _{DH}	Data Hold Time	10			ns
toeh	OE Hold Time	10			ns
toE	OE to Output Delay (2)				ns
twR	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.

2. See toE spec in AC Read Characteristics.

Data Polling Waveforms



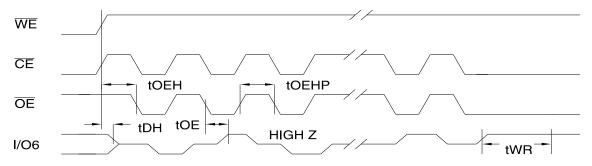
Toggle Bit Characteristics (1)

Symbol	Parameter	Min	Тур	Max	Units
t _{DH}	Data Hold Time	10			ns
toeh	OE Hold Time	10			ns
toE	OE to Output Delay (2)				ns
toehp	OE High Pulse	150			ns
twR	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.

2. See toE spec in AC Read Characteristics.

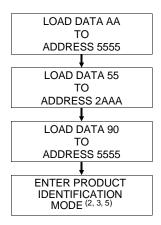
Toggle Bit Waveforms (1, 2, 3)



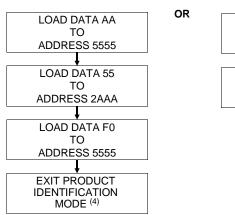
Notes: 1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit. The toehp specification must be met by the toggling input(s).

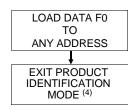
- 2. Beginning and ending state of I/O6 will vary.
- 3. Any address location may be used but the address should not vary.

Software Product Identification Entry (1)

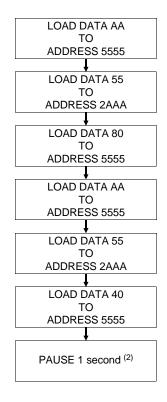


Software Product Identification Exit (1)





Boot Block Lockout Feature Enable Algorithm (1)



Notes for boot block lockout feature enable:

- 1. Data Format: I/O7 I/O0 (Hex); Address Format: A14 - A0 (Hex).
- 2. Boot block lockout feature enabled.

Notes for software product identification:

- 1. Data Format: I/O7 I/O0 (Hex); Address Format: A14 - A0 (Hex).
- 2. $A1 A18 = V_{IL}$.

Manufacture Code is read for $A0 = V_{IL}$;

Device Code is read for $A0 = V_{IH}$.

- The device does not remain in identification mode if powered down.
- 4. The device returns to standard operation mode.
- Manufacturer Code: 1FH Device Code: 13H





Ordering Information (1)

tACC	I _{CC} (mA)		Ondering Code	Dealsons	On andian Banna	
(ns)	Active	Standby	Ordering Code	Package	Operation Range	
90	50	0.1	AT49F040-90JC AT49F040-90PC AT49F040-90TC	32J 32P6 32T	Commercial (0° to 70°C)	
	50	0.3	AT49F040-90JI AT49F040-90PI AT49F040-90TI	32J 32P6 32T	Industrial (-40° to 85°C)	
120	50	0.1	AT49F040-12JC AT49F040-12PC AT49F040-12TC	32J 32P6 32T	Commercial (0° to 70°C)	
	50	0.3	AT49F040-12JI AT49F040-12PI AT49F040-12TI	32J 32P6 32T	Industrial (-40° to 85°C)	
150	50	0.1	AT49F040-15JC AT49F040-15PC AT49F040-15TC	32J 32P6 32T	Commercial (0° to 70°C)	
	50	0.3	AT49F040-15JI AT49F040-15PI AT49F040-15TI	32J 32P6 32T	Industrial (-40° to 85°C)	

Note: 1. The AT49F040 has as optional boot block feature. The part number shown in the Ordering Information table is for devices with the boot block in the lower address range (i.e., 00000H to 03FFFH). Users requiring the boot block to be in the higher address range should contact Atmel.

Package Type		
32J	32 Lead, Plastic, J-Leaded Chip Carrier Package (PLCC)	
32P6	32 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)	
32T	32 Lead, Thin Small Outline Package (TSOP)	